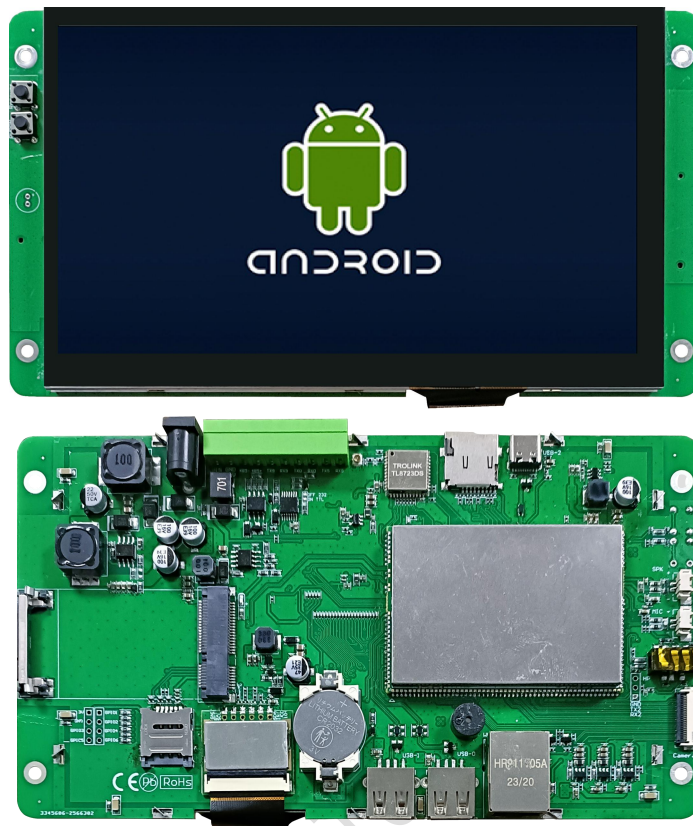


DMG10600T070_32WTC



System Hardware

Properties	Parameters
Motherboard level	Industrial-grade
CPU	RK3566, Quad-core ARM Cortex-A55, 1.8GHz Processor
OS	Android 11
Storage	8Gbytes eMMC
RAM	2Gbytes LPDDR4

Display Parameters

Properties	Parameters	Description
Size	7.0 inch	-
LCD Type	IPS, TFT LCD	-
Viewing Angle	85° /85° /85° /85°	Wide viewing angle, high contrast, and good color reproduction
Active Area (AA)	154.08mm(W)×85.92mm (H)	-
Resolution	1024×600	-
Backlight Service Life	>20000 Hrs	Backlight service life refers to the period the LED backlight operates under test conditions until brightness decreases to 50% of the initial level
Brightness	250nit	100-level brightness adjustment (Flickering may occur at 1%-30% of max brightness; not recommended for use in this range)

Note: Use dynamic screen saver to prevent afterimages from prolonged fixed page display.

Touch Parameter

Properties	Parameters
Touch Type	Capacitive touch panel
Structure	G+G structure with tempered glass surface

Power Supply

Properties	Min	Typ	Max	Unit
Power Voltage	11.0	12.0	36.0	V

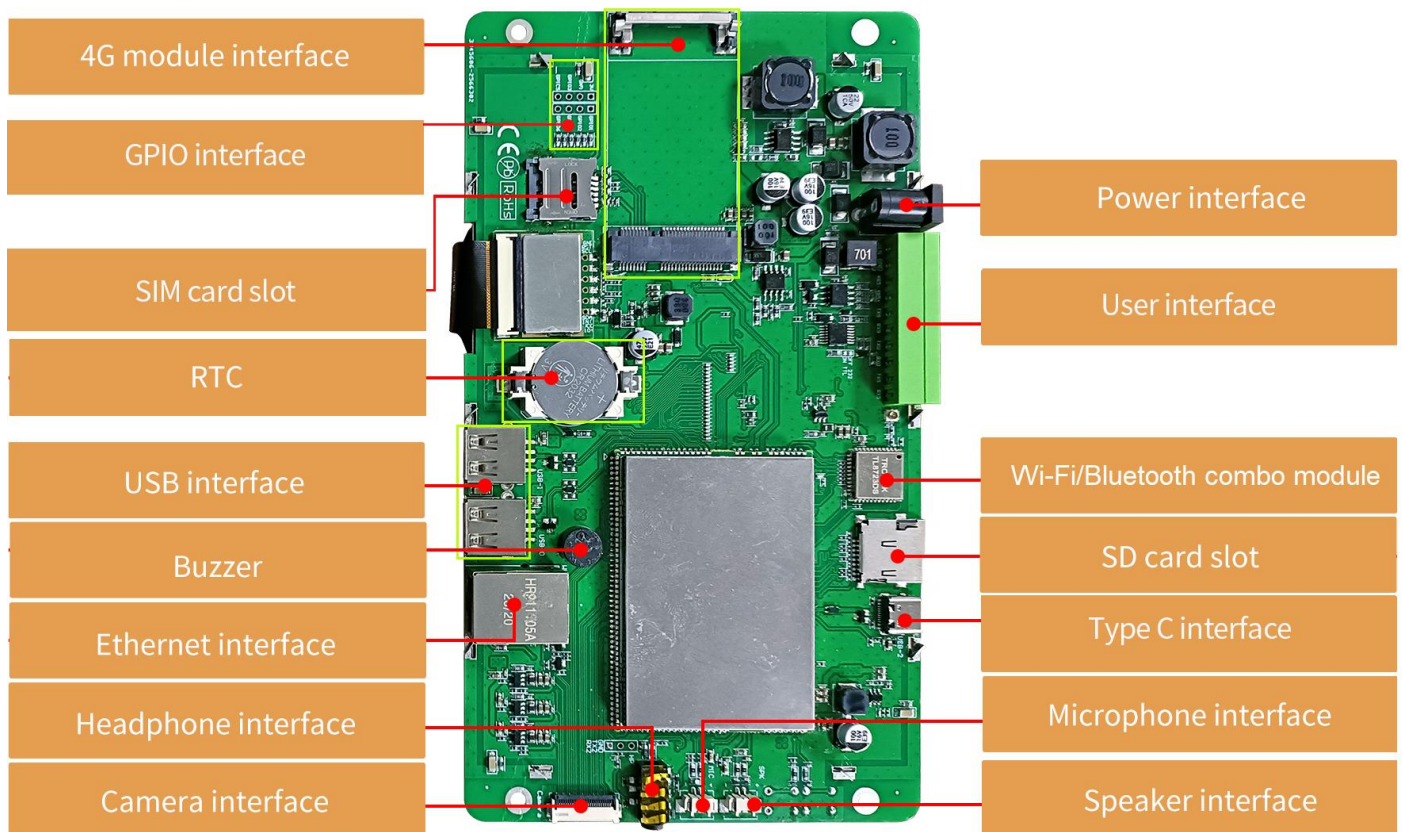
Recommended power supply:12V 1A DC.

Reliability Test

Properties	Conditions	Min	Typ	Max	Unit
Working Temperature	60%RH at 12V voltage	-20	25	70	℃
Storage Temperature	-	-30	25	80	℃
Working Humidity	25℃	10%	60%	90%	RH
Conformal Coating	Y				
ESD	Air: ±8KV, Contact: ±6K				
RE	Class B				
CE Certification	Y				

● Peripherals and Interfaces

Properties	Description
User Interface	10Pin_3.81mm horizontal socket, power interface (3PIN_Φ2.0DH)
COM	RS232*2 (COM5 & COM9), RS485*1(COM7), RS232/TTL*1 (COM0, RS232 default)
USB	USB 2.0*2 (HOST), Type C*1 (OTG)
Headphone	3.5mm spacing interface *1
Speaker	2Pin_1.25mm interface *1
Microphone	2Pin_1.25mm interface *1
4G module	Factory not configured, customizable to add
Camera	MIPI (24Pin_0.5mm interface)
SD card	Max. 64G
LAN	10/100Mbps
Wi-Fi	IEEE 802.11Bb/g/n,2.4GHz, Bluetooth
Bluetooth	4.2GHz
RTC	Accuracy: ±20ppm @25℃
GPIO Interface	GPIO*6

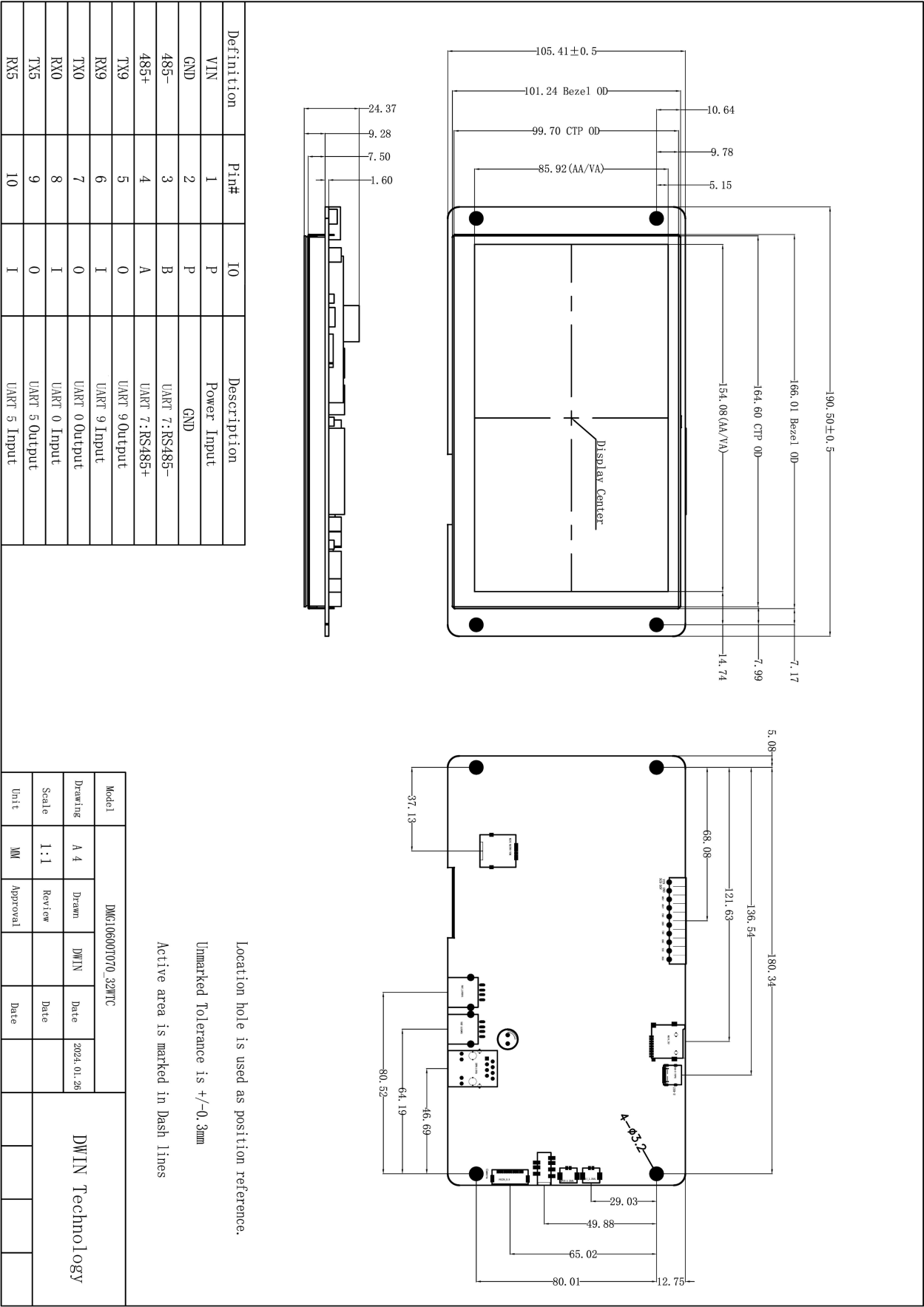


Development Platform

Development	
Android	Java, Kotlin, C++

Packing Capacity & Dimension

Dimension				
Dimension	190.50(W)×105.41(H)×24.37(T)mm			
Net Weight	340g			
Packing Capacity				
Model	Size	Layer	Quantity/Layer	Quantity (Pcs)
Carton1:	220mm(L)×160mm(W)×47mm	-	-	-
Carton2:	250mm(L)×200mm(W)×80mm	2	1	2
Carton3:	320mm(L)×270mm(W)×80mm	2	2	4
Carton4:	450mm(L)×350mm(W)×300mm	1	10	10
Carton5:	600mm(L)×450mm(W)×300mm	1	20	20



Revision Records

Rev.	Revise Date	Content	Editor
00	2025-02-17	First Edition	Chen
01	2025-03-12	Add the description of Bluetooth	Chen

Please contact us if you have any questions about the use of this document or our products, or if you would like to know the latest information about our products:

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Thank you all for continuous support of DWIN, and your approval is the driving force of our progress!

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